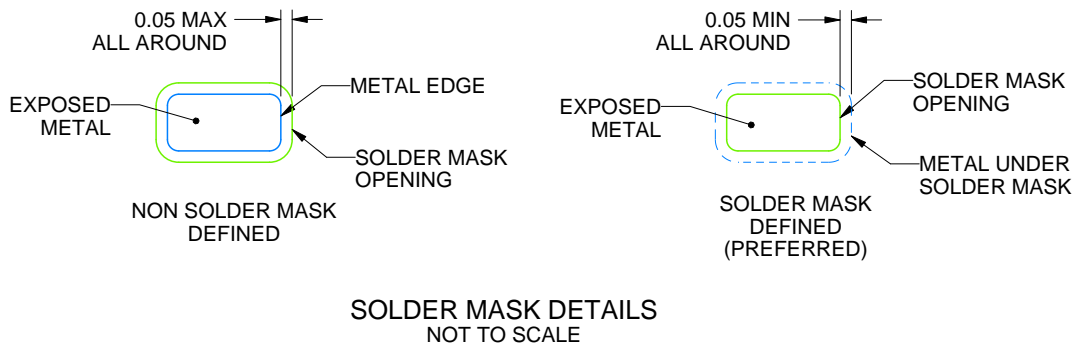
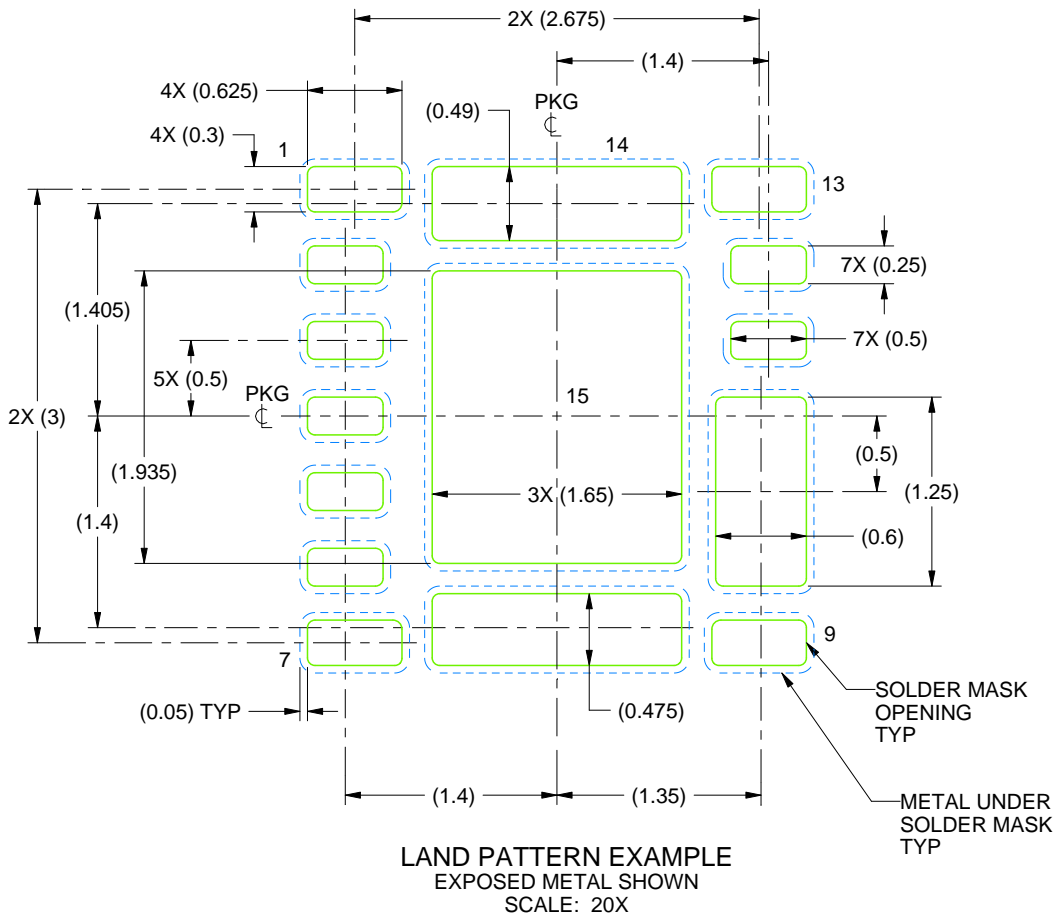


EXAMPLE BOARD LAYOUT

SIT0015A

MicroSiP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



4228472/D 01/2026

NOTES: (continued)

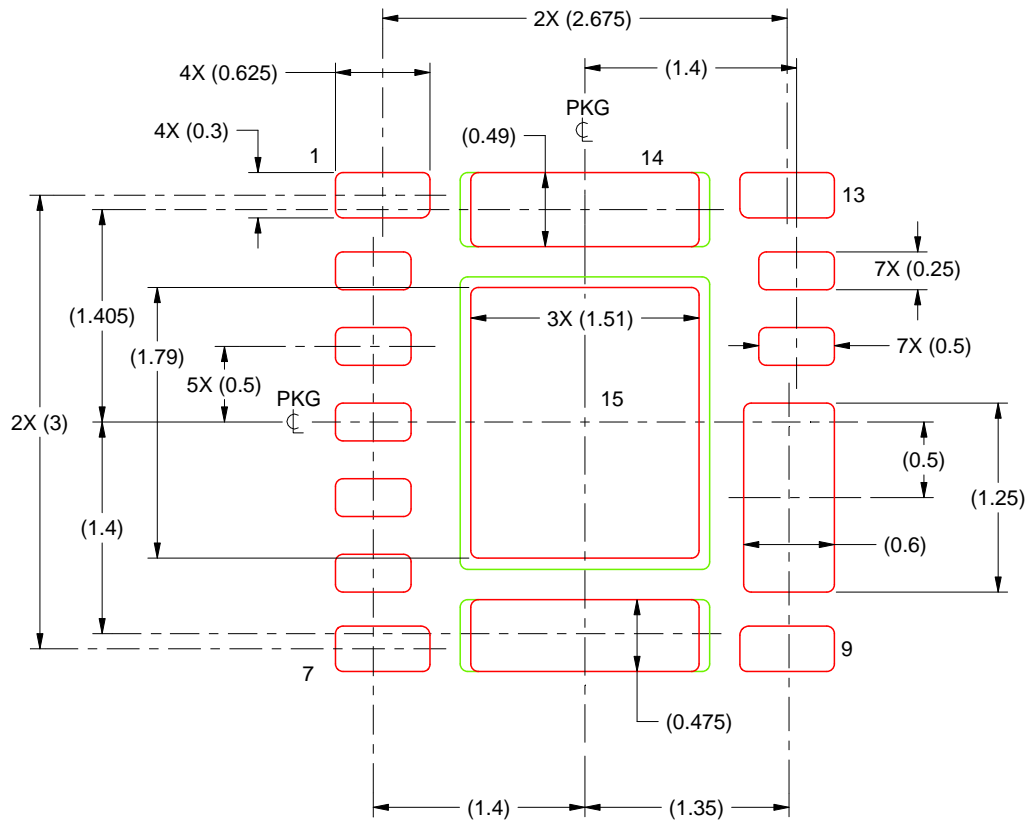
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

SIT0015A

MicroSiP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:20X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
PAD 8: 92%
PAD 14: 92%
PAD: 15: 85%

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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